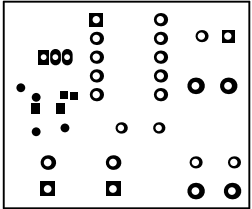
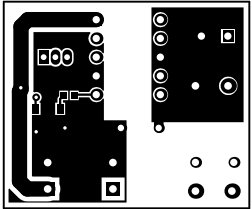


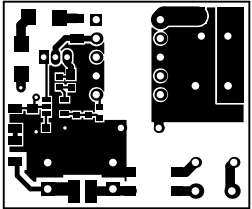
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8787	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/7/2013	12:22:49 PM	TEXAS INSTRUMENTS



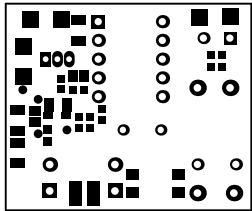
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/7/2013 12:22:49 PM	TEXAS INSTRUMENTS	



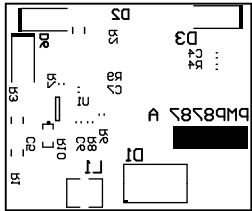
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LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/7/2013 12:22:50 PM	TEXAS INSTRUMENTS	



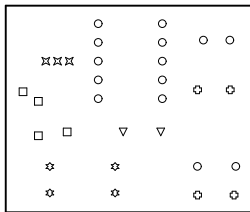
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LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/7/2013 12:22:50 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8787	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/7/2013 12:22:51 PM	TEXAS INSTRUMENTS	



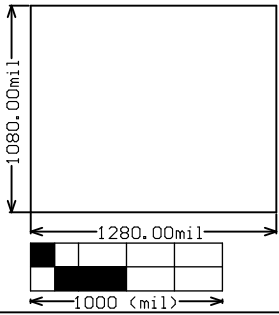
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8787	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/7/2013 12:22:51 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	4	18mil (0.457mm)	PTH	Round
×	3	29.528mil (0.75mm)	PTH	Round
▽	2	33.465mil (0.85mm)	PTH	Round
○	14	37.402mil (0.95mm)	PTH	Round
*	4	39.37mil (1mm)	PTH	Round
⊙	4	40mil (1.016mm)	PTH	Round
	31 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8787	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/7/2013 12:22:51 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8787	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/7/2013 12:22:52 PM	TEXAS INSTRUMENTS	

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